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AMENDMENTS TO THE CLAIMS

Applicant submits below a complete listing of the current claims, including marked-up claims with insertions indicated by underlining and deletions indicated by strikeouts and/or double bracketing. This listing of claims will replace all prior versions, and listings, of claims in the application:

- 1. (Withdrawn) An apparatus comprising:
 - a source of an incident electromagnetic wave;
 - a first plate of material transparent to the electromagnetic wave; and
- a layer of phase shift material having defined therethrough a polygonal window with at least six sides.
- 2. (Withdrawn) The apparatus according to claim 1, wherein said layer is adapted to define features of a semiconductor device.
- 3. (Withdrawn) The apparatus according to claim 1, wherein said polygonal window is octagonal.
- 4. (Withdrawn) The apparatus according to claim 1, wherein said polygonal window has such a number of sides as to form an approximately circular shape.
- 5. (Withdrawn) The apparatus according to claim 1, wherein said layer of phase shift material causes a 180° phase shift of the incident electromagnetic wave.
- 6. (Withdrawn) The apparatus according to claim 1, wherein said layer of phase shift material at least partially absorbs the incident electromagnetic wave at the wavelength used.

7. (Currently amended) A method of defining contacts on an integrated circuit device using an electromagnetic incident wave including:

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providing an integrated circuit device substrate, a first plate of material transparent to the electromagnetic incident wave placed over the substrate, and a layer of phase shift material having defined therethrough a regular polygonal polygon-shaped etch window with at least six sides; and

directing the electromagnetic incident wave at the substrate through the layer of phase shift material and first plate.

- 8. (Currently amended) The method according to claim 7, wherein the layer causes a 180° phase shift of the electromagnetic incident wave.
- 9. (Currently amended) The method according to claim 7, wherein the layer partially absorbs the electromagnetic incident wave.
- 10. (Withdrawn) An integrated circuit contact formed by directing an electromagnetic wave at a substrate through a first plate of material transparent to the electromagnetic wave placed over the substrate, and a layer of phase shift material placed over the first plate having defined therethrough a polygonal etch window with at least six sides.
- 11. (Withdrawn) The integrated circuit contact according to claim 10, formed by an octagonal window.
- 12. (Withdrawn) The integrated circuit contact according to claim 10, formed by a polygonal etch window having such a number of sides as to form an approximately circular shape.
- 13. (Withdrawn) The integrated circuit contact according to claim 12, wherein the layer of phase shift material causes a 180° phase shift of the photoelectric wave.

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14. (Withdrawn) The integrated circuit contact according to claim 10, wherein the layer made of transparent material partially absorbs the photoelectric wave.

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